

#### Description

The DMG3401LSN uses advanced trench technology to provide excellent R<sub>DS(ON)</sub>, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

### **General Features**

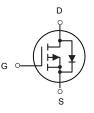
 $V_{DS}$  = -30V, $I_D$  = -6A R<sub>DS(ON)</sub> <35m $\Omega$  @ V<sub>GS</sub>=10V

## Application

High power and current handing capability Lead free product is acquired Surface mount package PWM applications Load switch Power management







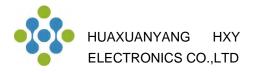
P-Channel MOSFET

## Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
DMG3401LSN	SOT-23	HXY MOSFET	3000

## Absolute Maximum Ratings (T<sub>A</sub>=25<sup>°</sup>C unless otherwise noted)

Symbol	Parameter	Limit	Unit
Vds	Drain-Source Voltage	-30	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
lo	Drain Current-Continuous	-6	А
Ідм	Drain Current-Pulsed (Note 1)	-24	А
PD	Maximum Power Dissipation	1.32	W
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	°C
Reja	Thermal Resistance, Junction-to-Ambient (Note 2)	125	°C <i>I</i> W



Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-30			V	
$\triangle BV_{DSS} / \triangle T$	BV <sub>DSS</sub> Temperature Coefficient	Reference to $25^{\circ}C$ , I <sub>D</sub> =-1mA		-0.022		V/°C	
Basian	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =-10V , I <sub>D</sub> =-4A		28	35	m0	
Rds(on)		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-2A		40	55	mΩ	
V <sub>GS(th)</sub>	Gate Threshold Voltage		-1.0		-2.5	V	
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS-VDS, ID2500A		4.6		mV/°C	
l	Drain-Source Leakage Current	V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1		
I <sub>DSS</sub>		V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	5		uA		
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-4A		15		S	
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		13		Ω	
Qg	Total Gate Charge (-4.5V)			9.7			
Qgs	Gate-Source Charge	V <sub>DS</sub> =-15V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-4A		2.5		nC	
$Q_{gd}$	Gate-Drain Charge			3			
T <sub>d(on)</sub>	Turn-On Delay Time			16.4			
Tr	Rise Time $V_{DD}$ =-15V , $V_{GS}$ =-10V , $R_G$ =3.3 $\Omega$ ,			20.2			
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =-4A		55		ns	
T <sub>f</sub>	Fall Time			10			
Ciss	Input Capacitance			750			
Coss	Output Capacitance	V <sub>DS</sub> =-15V , V <sub>GS</sub> =0V , f=1MHz		150		pF	
Crss	rss Reverse Transfer Capacitance			127			
ls	Continuous Source Current <sup>1,4</sup>				-6.0	Α	
I <sub>SM</sub>	Pulsed Source Current <sup>2,4</sup>	$V_G=V_D=0V$ , Force Current			-24	А	
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =-1A , T <sub>J</sub> =25°C			-1.2	V	
trr	Reverse Recovery Time			18.3		nS	
Qrr	Reverse Recovery Charge	IF=-4A , dI/dt=100A/µs , Tյ=25℃		7.2		nC	

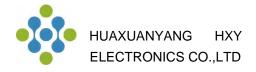
## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width  $\leq 300 us$  , duty cycle  $\leq 2\%$  3.The power dissipation is limited by 150°C  $\,$  junction temperature

4. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



#### **Typical Characteristics**

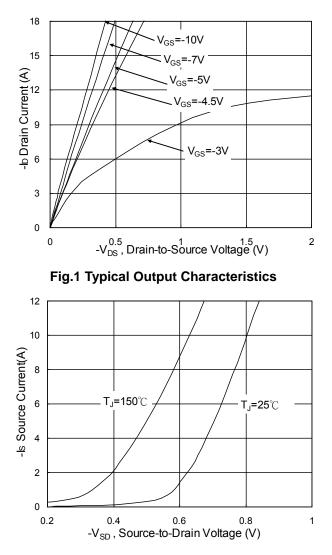


Fig.3 Forward Characteristics of Reverse

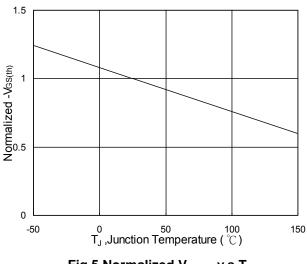


Fig.5 Normalized V<sub>GS(th)</sub> v.s T<sub>J</sub>

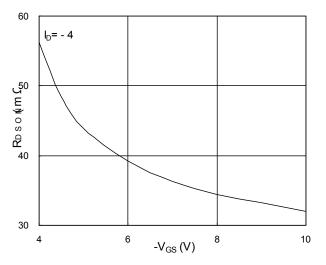


Fig.2 On-Resistance v.s Gate-Source

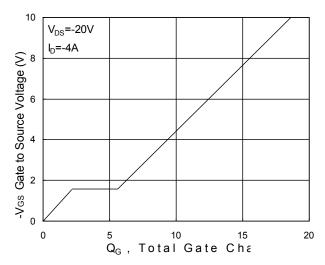


Fig.4 Gate-Charge Characteristics

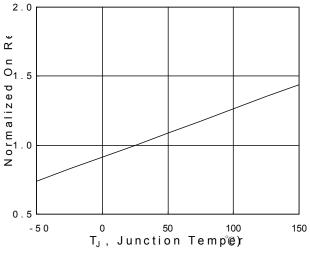
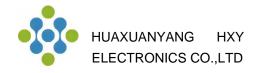


Fig.6 Normalized R<sub>DSON</sub> v.s T<sub>J</sub>



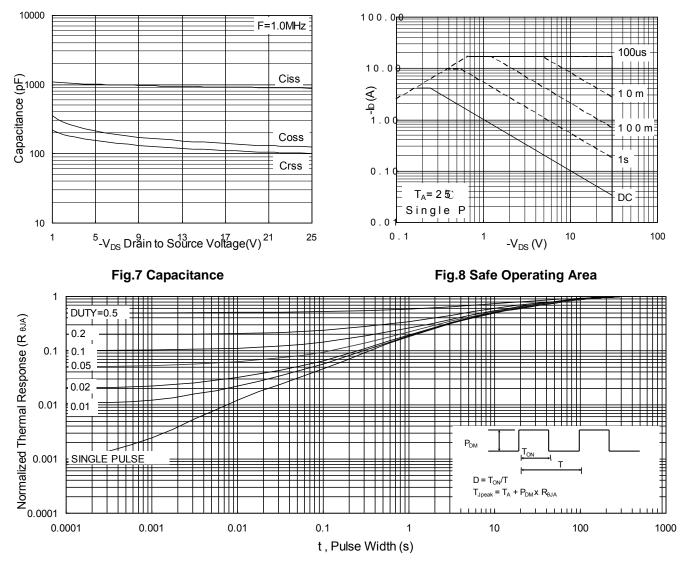


Fig.9 Normalized Maximum Transient Thermal Impedance

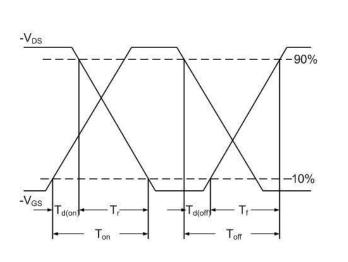


Fig.10 Switching Time Waveform

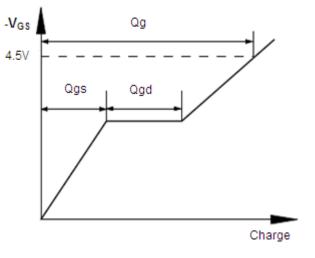
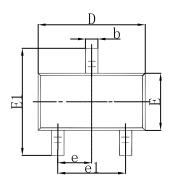
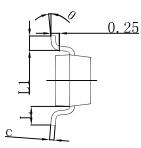


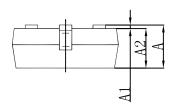
Fig.11 Gate Charge Waveform



# **SOT-23 Package Outline Dimensions**

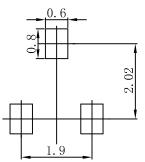






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950	0.950 TYP 0.037 TYP		7 TYP	
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

# SOT-23 Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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